

### IN THE CLAIMS

The pending claims are as follows:

1. (Original) A method for manufacturing printed circuit boards comprising:  
placing a component on a circuit board;  
partially printing attachment media on the circuit board with a pressurized squeegee head containing at least one blocking cap, wherein no attachment media is printed onto the component; and  
placing additional components on the circuit board.
2. (Original) The method of claim 1 wherein the component is a die.
3. (Original) The method of claim 2 further comprising testing the die prior to the partial printing step.
4. (Original) The method of claim 1 wherein the attachment media is solder paste, liquid flux or adhesive paste.
5. (Original) The method of claim 1 further comprising shipping the circuit board to another location before the partial printing step.
6. (Original) The method of claim 1 further comprising reflowing the attachment media and performing in-circuit testing.
7. (Original) The method of claim 1 wherein the pressurized squeegee head contains two blocking caps.

8. (Original) The method of claim 1 wherein the pressurized squeegee head contains three blocking caps.
9. (Original) The method of claim 1 wherein the pressurized squeegee head contains four or more blocking caps.
10. (Original) A method comprising:
  - placing a component on a circuit board;
  - shipping the circuit board to another location;
  - partially printing attachment media on the circuit board with a pressurized squeegee head containing at least one blocking cap, wherein no attachment media is printed onto the component; and
  - placing additional components on the circuit board.
11. (Original) The method of claim 10 wherein the component is a die.
12. (Original) The method of claim 11 further comprising testing the die prior to the partial printing step.
13. (Original) The method of claim 10 wherein the attachment media is solder paste, liquid flux or adhesive paste.
14. (Original) The method of claim 10 further comprising reflowing the attachment media.
15. (Original) The method of claim 14 further comprising performing in-circuit testing.

16. (Original) A method for manufacturing printed circuit boards comprising:  
placing a die on a circuit board;  
partially printing solder paste on the circuit board with a pressurized squeegee head  
containing at least one blocking cap, wherein no solder paste is printed onto the die; and  
placing additional components on the circuit board.
17. (Original) The method of claim 16 further comprising testing the die prior to the partial  
printing step.
18. (Original) The method of claim 17 further comprising shipping the circuit board to  
another location before the partial printing step.
19. (Original) The method of claim 18 further comprising reflowing the solder paste.
20. (Original) The method of claim 19 further comprising performing in-circuit testing.